ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES ®	© Co	terial Compo pyright 2005. IPC, Bannoc tternational and Pan-Ameri	kburn, Illinois	. All rights reserv	tion with lower	level p	arts, the	declaration	n encompa		er level mat	erials for	which th	item is an assembly e manufacturer has eclaration.
1752-2 1.1	.1 IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x						Form Type * Declaration Class * Distribute Class 6 - RoHS Yes/No, Homogeneous Mat					/laterials	and Mfg Informat	
Supplier Information														
Company Name *		Company Unique ID		Unique ID Au	uthority	Respo	onse Date	e *	Re	sponse Doc	ument ID			
Mindspeed Technologies	s, Inc						2010-11-23							
Contact Name * Title - Contact				Phone - Contact *		Email - Contact *								
Cynthia Ong		Program Manager		949-579-5515			cynthia.ong@mindspeed.com							
Authorized Representative * Title - Representative			Э	Phone - Representative *		Email - Representative *			* Su	Supplier Comments or URL for Additional Information				
CH Choong		Senior Quality Engin	eer	+6(04)-632 8036			ch.choong@mindspeed.com							
Requester Item Number	r	Mfr Item Number		Mfr Item Name		Effectiv	/e Date	Version	sion Manufacturing		g Site Weight *		OM	Unit Type
M21131G-23		M21131G-23		35HFCBGA 1156				Α	ASE, Taiwan		13,756.4	.4 mg		EACH
Alternate Recommenda	ation			NA			Alternate	ate Item Comments NA					•	
Manufacturing Proces	ss In	formation				•								
Terminal Plating / Grid Array	Materi	al	Terminal Ba	ase Alloy	J-STD-020 MSL Ra	ating	Peak Prod	cess Body	Temperatu	re Max Time	at Peak Tem	perature	Number o	of Reflow Cycles
SAC N/A				5		245		245 C	C 40 :		seconds 3			
Comments			l		1		l			1				
NA														

Save the fields in this form to a file Export Data Import fields from a file into this form		Locked
RoHS Material Composition Declaration	Declaration Type	* Simplified
RoHS Directive 2002/95/EC RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexaval 2002/95/EC Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Ca		rominated Biphenyls (PBB),
upplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is at Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws the upplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification ritten agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and or remedies provided as part of that agreement, will be the emedies for issues that arise regarding information the Supplier provides in this form.	nat implement the RoHS Direct applier has not independently von in this paragraph. If the Com	ive. Company acknowledges that erified information provided by others, npany and the Supplier enter into a
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions	Supplier Acceptance *	Accepted
exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then sel bove and choose all applicable exemptions.	lect the corresponding re	esponse in the RoHS Declaration
Exemption List Version EL-2006/690/EC		
15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.		
Declaration Signature		

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier	Digital	Signature
----------	---------	-----------

Homogeneous Material Composition Declaration for Electronic Products

Subltem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

Item/SubItem	Homogeneous	geneous		l				_		Unit of	Tolerance		a
Name	Material	Weight	Unit of Measure	Level	Substance Category	Substance	CAS	Exempt	Weight	Unit of Measure	-	+	PPN
M21131G-23	Die	386.83	mg	С	GROUP-C	Silicon	7440-21-3		386.83	mg			999,
	Heatslug	9,697	mg	С	GROUP-C	Copper	7440-50-8		9,633.96	mg			993,
				С	GROUP-C	Chrome	-		4.8485	mg			500
				В	Nickel/Nickel Compou	Nickel	7440-02-0		58.182	mg			4,22
	Adhesive/ TIM	180	mg	С	GROUP-C	Others	Trade Secret		18	mg			99,9
				С	GROUP-C	Alumina	01344-28-1		162	mg			899,
	Solder ball	1,018.09	mg	С	GROUP-C	Ag	7440-22-4		30.5427	mg			30,0
				С	GROUP-C	Cu	7440-50-8		5.09045	mg			5,00
				С	GROUP-C	Sn	7440-31-5		982.4568	mg			964,
	Substrate	2,422.1	mg	С	GROUP-C	Ag	7440-22-4		2	mg			825.
				С	GROUP-C	CaO	1305-78-8		151	mg			62,3
				В	Antimony/Antimony C	Sb2O3	1309-64-4		22	mg			1,59
				С	GROUP-C	Brome compounds			72	mg			29,7
				С	GROUP-C	SiO2	7631-86-9		352	mg			145,
				С	GROUP-C	Polyphenylene ether (Pi	•		382	mg			157,
				Α	Lead/Lead Compound	Pb	7439-92-1		3	mg			1,23
				В	Bismuth/Bismuth Com	Bi	7440-69-9		5	mg			363.
				С	GROUP-C	Sn	7440-31-5		56	mg			23,1
				С	GROUP-C	MgO	1309-48-4		38	mg			15,6
				С	GROUP-C	Epoxy resin			51	mg			21,0
				С	GROUP-C	Talc	14807-96-6		10	mg			4,12
				С	GROUP-C	BaSO4	7727-43-7		12	mg			4,95
				С	GROUP-C	AI2O3	1344-28-1		95	mg			39,2

			В	Arsenic/Arsenic Comp	As	7440-38-2	0.1	mg	7.2693
			С	GROUP-C	Cu	7440-50-8	1,171	mg	483,46
Underfill	42	mg	С	GROUP-C	Phenolic resin	9003-35-4	8.4	mg	199,99
	•		С	GROUP-C	Amine type accelerator	Trade Secret	2.1	mg	49,999
			С	GROUP-C	Silicon dioxide	60676-86-0	19.32	mg	459,99
			С	GROUP-C	Additives	Trade Secret	2.1	mg	49,999
			С	GROUP-C	Bisphenol F type liquid	£9003-36-5	8.4	mg	199,99
			С	GROUP-C	Bisphenol A type liquid	25068-38-6	1.26	mg	29,999
			С	GROUP-C	Carbon black	1333-86-4	0.42	mg	9,999.9
Bump	10.42	mg	С	GROUP-C	Sn	7440-31-5	6.5646	mg	629,99
	•	•	A	Lead/Lead Compound	Pb	7439-92-1	3.8554	mg	369,99